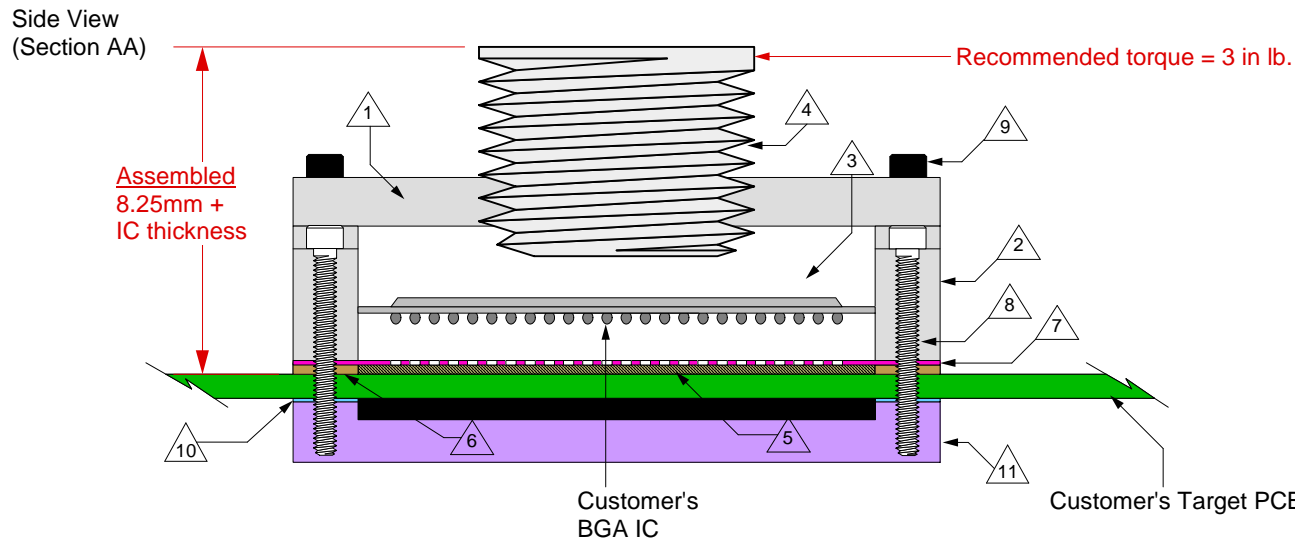
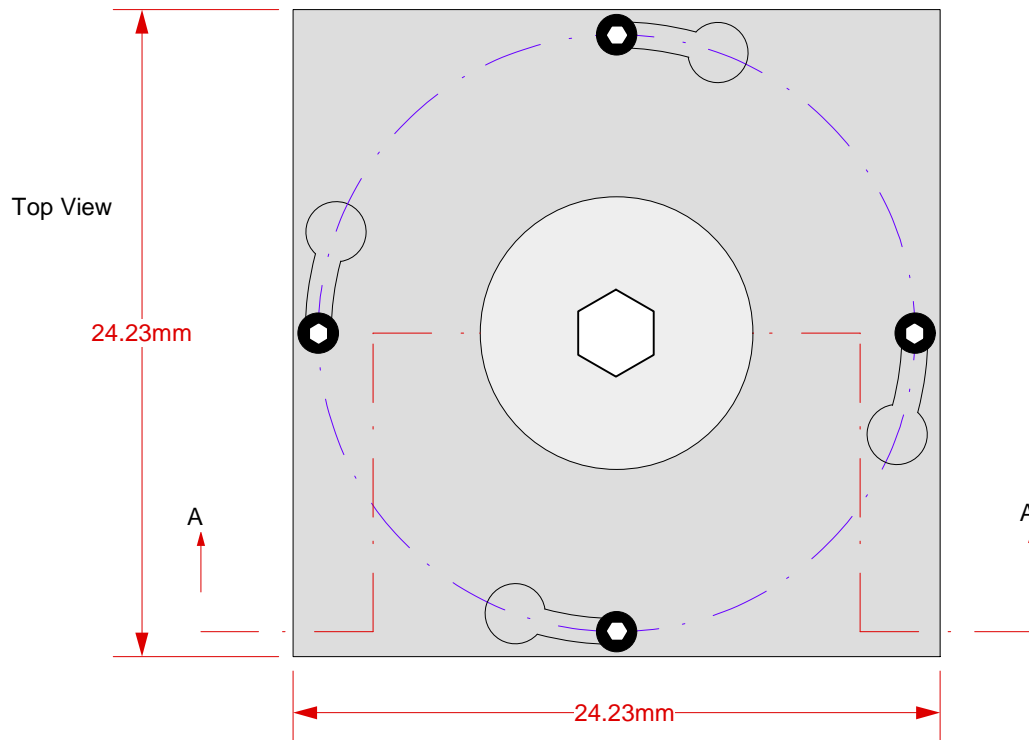



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

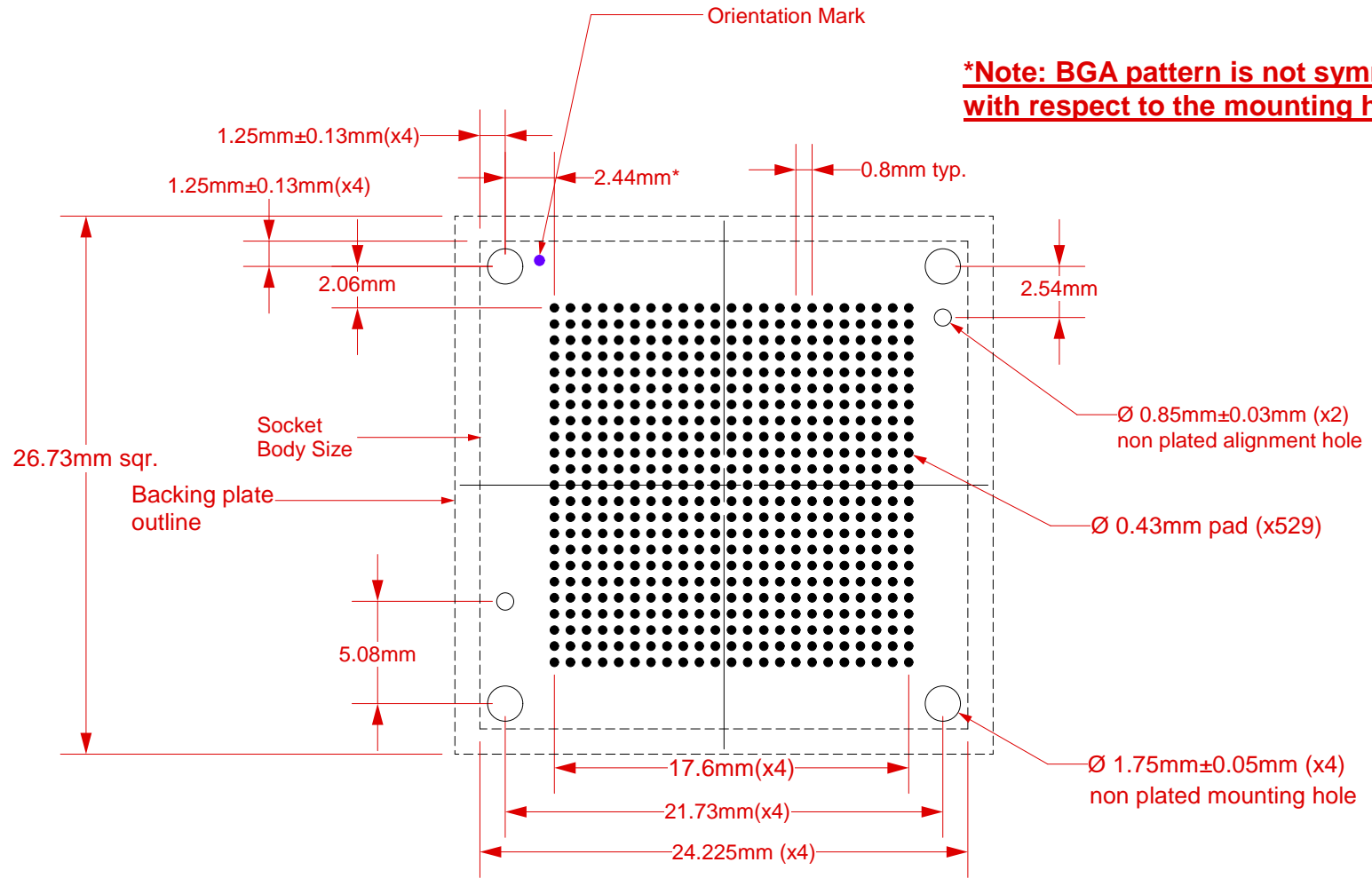


- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Non-clad FR4.
Thickness = 0.745mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread. |
| 10 | Insulation plate: Kapton polyamide film.
Thickness: 0.25mm |
| 11 | Backing plate: Black anodized Aluminum.
Thickness = 4 mm. |

	SG-BGA-6217 Drawing	Status: Released	Scale: -	Rev: C
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 03/5/07	
		File: SG-BGA-6217 Dwg	Modified: 7/20/09, AE	

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



***Note: BGA pattern is not symmetrical with respect to the mounting holes.**


Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

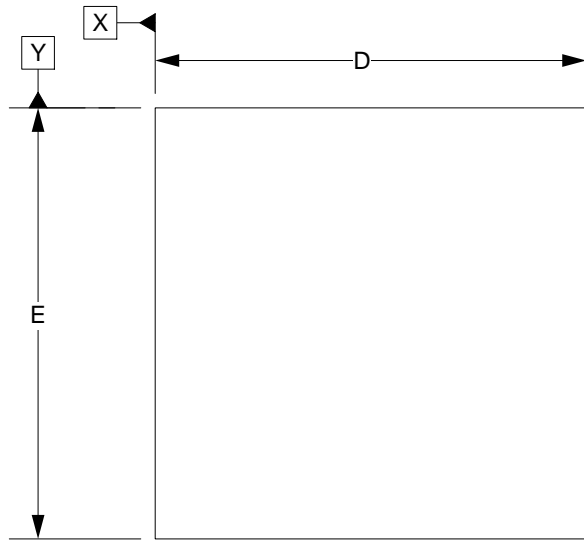
Target PCB Recommendations

Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

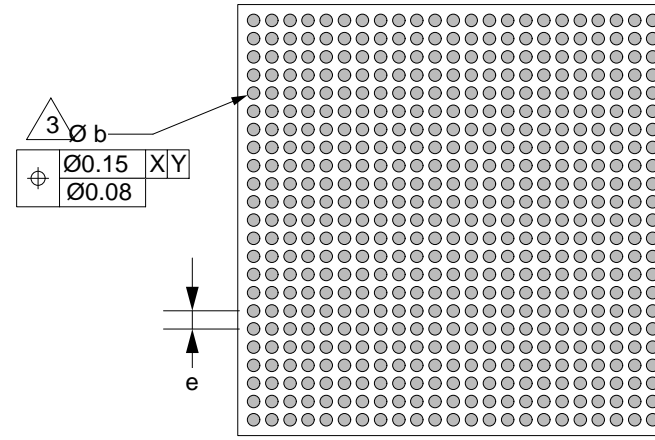
NOTE: Backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

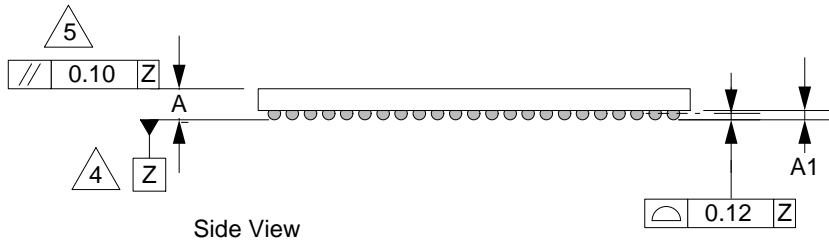
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-6217 Drawing</p>	<p>Status: Released</p>	<p>Scale: -</p>	<p>Rev: C</p>
	<p>Drawing: J. Glab</p>	<p>Date: 03/5/07</p>		
	<p>File: SG-BGA-6217 Dwg</p>	<p>Modified: 7/20/09, AE</p>		



Top View



Bottom View




Side View

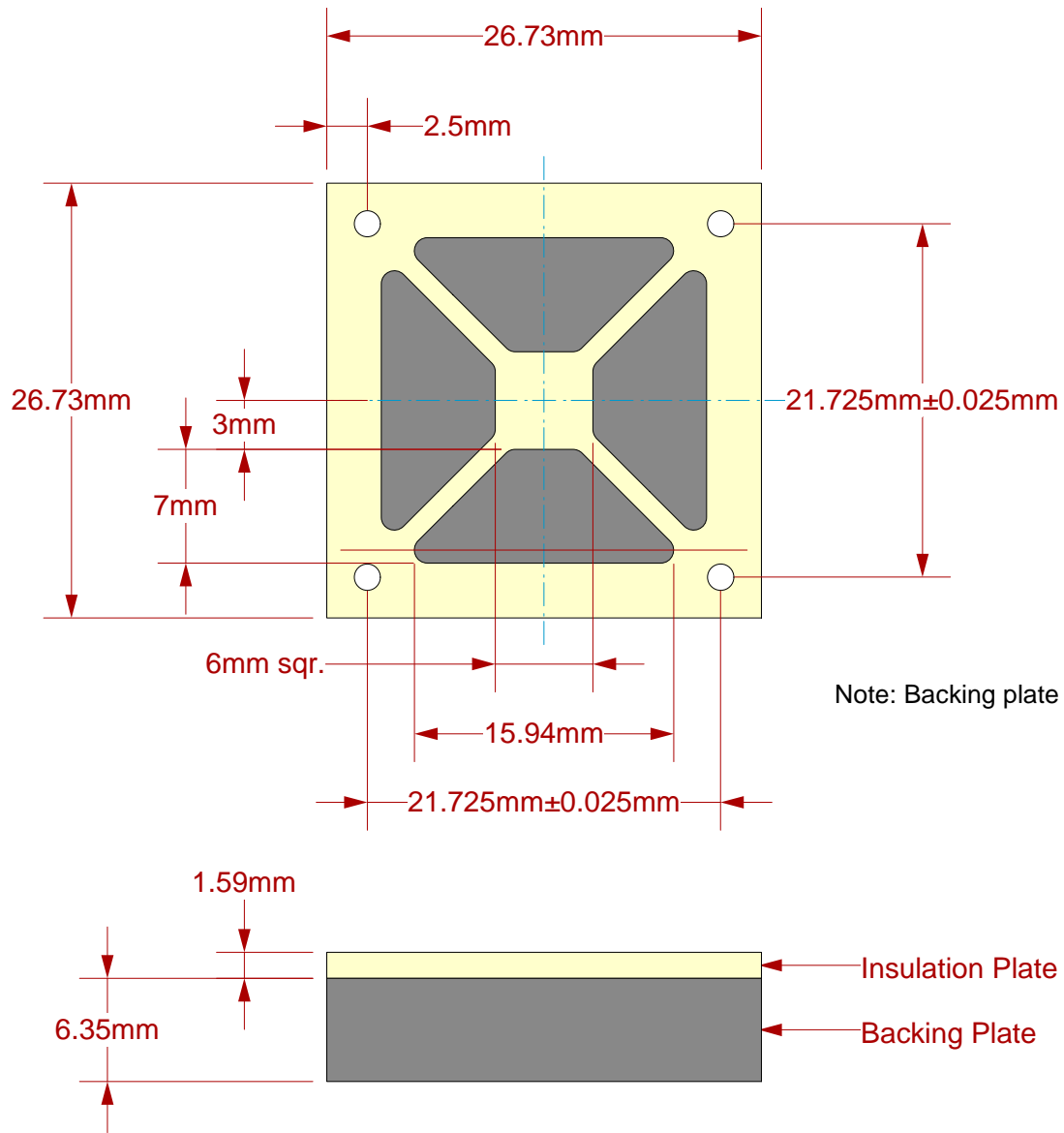
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.


DIM	MIN	MAX
A		1.64
A1	0.35	0.45
b	0.47	0.57
D	19.0 BSC	
E	19.0 BSC	
e	0.8 BSC	

Array: 23 X 23

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		File: SG-BGA-6217 Dwg	Modified: 7/20/09, AE	



Description: Insulation and backing plate.

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	<p>Drawing: J. Glab</p>		<p>Date: 03/5/07</p>		
	<p>File: SG-BGA-6217 Dwg</p>		<p>Modified: 7/20/09, AE</p>		

All tolerances are ±0.13mm